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Re: Inventor(s): Shinichi Kurita, Wendell T. Blonigan, and Akihiro Hosokawa
Title: DUAL SUBSTRATE LOADLOCK PROCESS EQUIPMENT

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Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 31 pages.
☒ Drawings totaling 13 pages, Formal ☒ Informal.
☒ Executed Declaration and Power of Attorney.
☒ Assignment of the invention to Applied Materials, Inc.
☒ Assignment Recordation Cover Sheet

FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
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DUAL SUBSTRATE LOADLOCK PROCESS EQUIPMENT

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FIELD OF THE INVENTION

The present invention relates to substrate processing systems, and, more particularly, to loadlock systems for handling substrates.

BACKGROUND OF THE INVENTION

Substrates such as, for example, glass panels used in applications such as television and computer displays may be fabricated using sequential steps including physical vapor deposition (PVD), chemical vapor deposition (CVD), etching, and annealing to produce the desired device. These steps may be carried out using a variety of processing systems having multiple chambers. One such system is known as a "cluster tool". A cluster tool generally includes a central wafer handling module or transfer chamber and a number of peripheral chambers including a loadlock chamber through which workpieces are introduced into and removed from the system and a plurality of other chambers for carrying out processing steps such as heating, etching, and deposition. The cluster tool also generally includes a robot for transferring workpieces between the chambers.

The processing of large glass substrates used for displays is in some ways similar to the processing of other types of substrates such as semiconductor wafers. Such glass substrates, however, are often larger than typical silicon wafers. For example, glass substrates may have dimensions of 550 mm by 650 mm, with trends towards even larger sizes such as 650 mm by 830 mm and larger, to permit the formation of larger displays. The use of large glass substrates introduces complexities into processing that may not be present when processing other types of substrates. For example, in addition to their size, glass substrates used for displays are typically rectangular in shape. The large size and shape of glass substrates can make them difficult to transfer from position to position within a processing system when compared with smaller, circular-shaped substrates. As a result, systems for processing glass substrates generally require larger chambers, apertures, and transfer mechanisms. In addition, it is known to utilize large cassettes holding approximately 12 substrates within the loadlock in order to supply a large number of substrates to the processing chambers for batch processing operations. The need for larger chamber sizes to handle large substrates, as well as the use of large substrate

1 cassettes in the loadlock, also leads to a requirement for larger and more powerful
2 vacuum pumps, power supplies, control mechanisms and the like and a corresponding
3 increase in system cost.

4 In addition, glass substrates often have different thermal properties than silicon
5 substrates. In particular, glass generally has a relatively low thermal conductivity, which
6 can make it more difficult to uniformly heat and cool the substrate. Temperature
7 gradients may occur across the glass substrate, which can lead to undesirable stresses in
8 the substrate upon cooling. The heat loss near the substrate edges tends to be greater
9 than near the center. Temperature gradients during processing can also result in the
10 components formed on the substrate surface having non-uniform electrical (and
11 structural) characteristics. As a result, to maintain adequate temperature control, heating
12 and cooling operations are often performed relatively slowly. As the system components
13 become larger in size, these steps may be slowed even more due to the longer time it
14 generally takes to heat and cool large components in a large volume chamber. These
15 slow operations tend to lower the system throughput.

16 SUMMARY OF THE PREFERRED EMBODIMENTS

17 Certain embodiments of the present invention relate to loadlock devices for use in
18 substrate processing systems that are relatively compact in size and that can achieve
19 substrate transfer, cooling and/or heating operations in an efficient manner.

20 One embodiment relates to a loadlock having a first support structure adapted to
21 support a first substrate and a cooling plate adapted to support a second substrate.

22 Another embodiment relates to a loadlock having a first support structure to
23 support one unprocessed substrate and a second support structure to support one
24 processed substrate. The first support structure is located above the second support
25 structure and an elevator is provided to control the vertical position of the support
26 structures. The loadlock also includes a first aperture to permit insertion of an
27 unprocessed substrate into the loadlock and removal of a processed substrate from the
28 loadlock, as well as a second aperture to permit removal of an unprocessed substrate
29 from the loadlock and insertion of a processed substrate into the loadlock. A cooling plate
30 having a surface adapted to support a processed substrate is also included in the
31 loadlock. The cooling plate may be designed to have multiple zones for preferentially
32 controlling the cooling rate of a processed substrate thereon. A heating device is also
33 provided in the loadlock above the first support structure. The heating device may be
34 used to heat an unprocessed substrate on the first support structure prior to inserting the

unprocessed substrate into another chamber for subsequent processing.

Another embodiment relates to a semiconductor processing system having at least one processing chamber, a transfer chamber connected to the processing chamber, and a loadlock connected to the transfer chamber. The loadlock includes a single substrate upper support structure and a single substrate lower support structure, as well as a transfer aperture to transfer a single substrate between the transfer chamber and the loadlock. The loadlock also includes an elevator for raising and lowering the supports and a cooling plate positioned to accept a single substrate from the single substrate lower support structure.

Another embodiment relates to a loadlock including a loadlock chamber and a support structure in the chamber. The support structure is adapted to accept a single substrate from a robot arm. A cooling plate is also located in the chamber and is positioned to accept a single substrate from the support structure. The support structure is movable relative to the cooling plate.

Another embodiment relates to a loadlock system having a first means for supporting only a single unprocessed substrate and a second means for supporting only a single processed substrate. The first means is located above the second means. The system also includes a delivery means for delivering a processed substrate to a cooling plate located in the loadlock system.

Embodiments of the present invention also relate to methods including utilizing a loadlock and methods for processing substrates. One such embodiment relates to a method for using a loadlock including delivering an unprocessed substrate to an upper support structure in the loadlock through an opening in the loadlock. The opening is closed and the loadlock evacuated to the desired pressure level. The unprocessed substrate is transferred to a chamber outside of the loadlock. A processed substrate is delivered from a chamber outside of the loadlock (such as, for example, a transfer chamber or other chamber in a processing system) to a lower support structure in the loadlock. The processed substrate is delivered from said lower support structure to a cooling plate in the loadlock, and the processed substrate is cooled.

Another embodiment relates to a method for processing substrates including delivering an unprocessed substrate to an upper support structure in a loadlock through a first opening in the loadlock. The opening is closed and the loadlock evacuated. The unprocessed substrate is delivered to a chamber outside of the loadlock through a second opening in the loadlock. A processed substrate is delivered from a chamber outside of the loadlock to the lower support structure through the second opening in the

loadlock. The second support structure is lowered to deliver the processed substrate to a cooling plate in the loadlock.

Still another embodiment relates to a method for processing a substrate including delivering one unprocessed substrate from an unprocessed substrate supply located outside of a loadlock to a first loadlock support structure inside of the loadlock, using a first robot. The unprocessed substrate is transferred from the first loadlock support structure to a transfer chamber using a second robot. The unprocessed substrate is transferred from the transfer chamber to at least one processing chamber to process the unprocessed substrate to form a processed substrate. The processed substrate is transferred from the at least one processing chamber to the transfer chamber. The processed substrate is transferred from the transfer chamber to a second loadlock support structure using the second robot. The second loadlock support structure may be located below the first loadlock support structure. The processed substrate is transferred from the second loadlock support structure to a cooling plate in the loadlock and cooled. The processed substrate is removed from the loadlock using the first robot.

Yet another embodiment relates to another method for processing substrates including delivering a single unprocessed substrate to an upper support structure in a loadlock and evacuating the loadlock. The single unprocessed substrate is delivered from the loadlock to the transfer chamber. A single processed substrate is delivered from a transfer chamber to a lower support structure in said loadlock. The single processed substrate is delivered from said lower support structure to a cooling plate in said loadlock. The loadlock is vented and the single processed substrate is delivered to a location external to the loadlock and the transfer chamber. Another single unprocessed substrate is delivered to the loadlock.

BRIEF DESCRIPTION OF THE DRAWINGS

Embodiments of the invention are described with reference to the accompanying drawings which, for illustrative purposes, are schematic and not drawn to scale.

Fig. 1 is a top schematic view of a cluster tool including a loadlock, transfer chamber, and processing chambers according to an embodiment of the present invention.

Fig. 2 is a cross-sectional view of a portion of the loadlock of Fig. 1 in accordance with an embodiment of the present invention.

Fig. 3 is a perspective view of a loadlock according to an embodiment of the present invention.

1 Fig. 4 is a perspective view of the loadlock of Fig. 3 including an outer body
2 section around an interior compartment according to an embodiment of the present
3 invention.

4 Fig. 5 is a perspective view of the loadlock of Figs. 3 and 4 including a cover
5 portion and a lower portion according to an embodiment of the present invention.

6 Fig. 6a is an exploded view of certain interior components of a loadlock according
7 to an embodiment of the present invention.

8 Fig. 6b is a perspective view of some of the loadlock components of Fig. 6 when
9 assembled together according to an embodiment of the present invention.

10 Figs. 7a-f illustrate a processing scheme in accordance with an embodiment of the
11 present invention.

12 Fig. 8 is a perspective view of a portion of a loadlock system in a load/unload
13 condition in accordance with an embodiment of the present invention.

14 Fig. 9 is a perspective view of a portion of a loadlock system in a cool down
15 condition in accordance with an embodiment of the present invention.

16 Fig. 10 is a cross-sectional view of a cooling plate with a coolant carrying channel
17 therein in accordance with an embodiment of the present invention.

18 Fig. 11 is a cross-sectional view of a cooling plate with a coolant-carrying channel
19 at a bottom portion of the cooling plate in accordance with an embodiment of the present
20 invention.

21 Fig. 12 is a cross-sectional view of a middle plate with a coolant carrying channel
22 therein in accordance with an embodiment of the present invention.

23 Fig. 13 is a cross-sectional view of a middle plate with a coolant carrying channel
24 at an upper portion of the middle plate in accordance with an embodiment of the present
25 invention.

26 Fig. 14 is a top view of a plate having a high emissivity area in accordance with an
27 embodiment of the present invention.

28 Fig. 15 is a cross-sectional view of a cooling plate and substrate support system
29 according to an embodiment of the present invention.

30 Fig. 16 is a top cross-sectional view of a cluster chamber according to an
31 embodiment of the present invention.

32 Fig. 17 is a top cross-sectional view of a cluster chamber according to an
33 embodiment of the present invention.

DETAILED DESCRIPTION

Certain preferred embodiments relate to loadlock systems and methods of operation. These loadlock systems may be used as part of a larger cluster type processing system. As illustrated in Fig. 1, one embodiment includes a cluster system having a central substrate handling module or transfer chamber 10, a number of peripheral process chambers 20, and at least one loadlock mechanism 30 for inserting substrates into the system and removing substrates from the system. The central transfer chamber 10 may include a robot 40 therein for picking up and delivering substrates between the various chambers. The term substrates includes substrates formed from a variety of materials including, but not limited to glasses, semiconductors, ceramics, metals, composites, and combinations thereof.

A preferred embodiment of the loadlock 30 is illustrated in the cross-sectional view of Fig. 2. The loadlock 30 preferably includes a dual substrate cassette 50, with an upper slot 51 for holding an unprocessed substrate and a lower slot 53 for holding a processed substrate. The upper slot 51 may preferably be located between an upper plate 54 and a middle plate 56 of the cassette 50. The lower slot 53 may preferably be formed between the middle plate 56 and a cooling plate 52, above a lower plate 76 of the cassette 50. The plates 54, 56 and 76 are assembled to form the cassette 50. The cooling plate 52 is almost entirely located within the cassette 50. However, it is preferably not connected to the cassette 50. Instead, flange portions 100, 102 of the cooling plate 52 are preferably attached to a frame member 64 that surrounds the cassette 50. This structure enables the cassette 50 to move independently of the cooling plate 52 by coupling the cassette to an elevator 58 (Fig. 3) through shaft 128. By moving the cassette 50 independently of the cooling plate 52, a substrate on supports 78, 80 within the lower slot 53 can be lowered onto and raised off of the cooling plate 52 by moving the cassette.

In certain preferred embodiments, a substrate on the cooling plate 52 may be cooled by positioning the cooling plate (with the substrate thereon) and the middle plate 56 very close to one another. By sandwiching the substrate between the cooling plate 52 and middle plate 56, the substrate can be cooled in an efficient manner. As will be discussed in more detail later, both the middle plate 56 and the cooling plate 52 may be water cooled and may have a high emissivity surface area.

Progressive views of the loadlock 30 are illustrated in Figs. 3-5. The cassette 50 may include an opening 62 for viewing the cassette interior during operation. Fig. 4 shows the loadlock 30 of Fig. 3, further including the loadlock body portion or frame member 64 surrounding the cassette 50. A window 66 may be provided for viewing the

1 interior of the cassette through opening 62, and a door 68 may be provided for accessing
2 the interior of the loadlock to insert and remove substrates. The elevator 58 may be
3 positioned below the cassette 50 and used to move the cassette 50 relative to the cooling
4 plate 52 and frame member 64. As shown in Fig. 2, the elevator 58 may include a shaft
5 128 attached to the bottom of the cassette 50 through a connection such one or more
6 connectors 130 and plate 132. The connectors 130 may be designed to be adjustable so
7 that the cassette 50 can be leveled if it becomes misaligned. Alternatively, the shaft 128
8 may be directly connected to the cassette 50.

9 Fig. 5 shows the loadlock 30 of Figs. 3 and 4, further including a top pressure
10 vessel portion or top cover 70 and a lower pressure vessel portion or bottom cover 72 to
11 define the loadlock chamber region. The top cover 70 and bottom cover 72 may be any
12 suitable structure capable of maintaining appropriate vacuum or other desired pressure
13 conditions and be capable of surviving elevated temperatures such as those encountered
14 during substrate heating. The loadlock 30 may also include a wheeled frame structure 74
15 for supporting and moving the loadlock 30.

16 Fig. 6a illustrates an exploded view of certain components in the loadlock 30
17 including components from the cassette 50, the cooling plate 52 and the frame member
18 64. Fig. 6b illustrates the cassette 50 assembled within the frame member 64. The
19 frame member 64 includes openings 96 and 98 on opposite sides, through which
20 substrates are inserted into and removed from the loadlock. Opening 96 may be on the
21 atmospheric side of the loadlock, and opening 98 may be on the transfer chamber side of
22 the loadlock.

23 The lower plate 76 of the cassette 50 preferably has a support structure including
24 the supports 78, 80 thereon for supporting a substrate 82. The cooling plate 52, (located
25 above the lower plate 76) may include apertures 84, 86 through which the supports 78, 80
26 may extend to support the substrate 82 in the lower slot 53. The middle plate 56
27 preferably has a support structure including supports 88, 90 thereon for supporting a
28 substrate 92 in the upper slot 51. Above the middle plate 56 (and the substrate 92) lies
29 the upper plate 54 and heating device 94. The heating device 94 may include, for
30 example, a resistance element or a heating lamp. Alternative embodiments may omit the
31 upper plate 54 and/or the heating device 94.

32 As illustrated in Fig. 6a, the heating device 94 may fit into a recess in the upper
33 plate 54 so that it moves with the cassette 50 and is always positioned close to the upper
34 support structure. Alternatively, the heating device 94 may be positioned above the upper
35 plate 54 as illustrated in Fig. 2 or at some other position in the loadlock. One preferred

1 use for the heating device is to preheat an unprocessed substrate prior to transferring the
2 substrate to other chambers. Preheating the substrate may free up one or more
3 processing chamber positions in the system which would otherwise be used as heating
4 chambers to heat the unprocessed substrate. By preheating the substrate in the
5 loadlock, such heating chambers may be eliminated. Embodiments may heat the
6 substrate to a desired temperature depending on the particular processing operation such
7 as, for example, a temperature in the range of approximately 100°C to 500°C or higher.
8 It may be possible to also use the loadlock for other types of heating operations, such as
9 annealing or ashing, if desired. For certain types of high temperature processing or
10 processing in which the substrate is heated in between other processing steps, separate
11 heating chambers may still be required.

12 Figs. 7a-f schematically illustrate several components of a loadlock as used during
13 one possible processing embodiment. Certain component sizes and shapes have been
14 altered relative to earlier figures for illustrative purposes. The components illustrated
15 include the lower plate 76, the cooling plate 52, and the middle plate 56. Lower supports
16 78, 80 are coupled to the lower plate and upper supports 88, 90 are coupled to the middle
17 plate 56. The lower plate 76 and middle plate 56 are coupled to one another to form
18 cassette 50 as indicated by the dashed lines. The lower supports 78, 80 extend through
19 apertures in the cooling plate 52. An atmospheric robot (not shown in Figs. 7a-f) delivers
20 into and removes substrates from the load lock through atmospheric opening 96 and door
21 68, and a transfer chamber robot (not shown in Figs. 7a-f) removes from and delivers
22 substrates into the loadlock through vacuum opening 98 and door 99. As seen in Figs.
23 7a-f, the cooling plate 52 is coupled to the frame 64 and does not move relative to the
24 openings 96, 98. The cassette 50 (which includes the lower plate 76, lower supports 78,
25 80, the middle plate 56, and the upper supports 88, 90), is moveable relative to the
26 openings 96, 98.

27 A condition when there are no substrates in the loadlock is illustrated in Fig. 7a.
28 This may be the condition at the beginning of a processing cycle. In one embodiment, a
29 processing method includes supplying an unprocessed substrate 92 to the loadlock. As
30 shown in Fig. 7b, upper supports 88, 90 are aligned with the opening 96 and an
31 unprocessed substrate 92 has been inserted into the loadlock through an atmospheric
32 opening from the direction indicated by the arrow. Next, the atmospheric opening door 88
33 is closed, the loadlock is evacuated and the cassette 50 is raised to place the lower
34 supports 78, 80 through openings 59 in the cooling plate 52 and into alignment with the
35 vacuum opening 98 as shown in Fig. 7c. Vacuum opening door 99 is opened so that a

1 processed substrate 82 can be delivered from a transfer (or other processing) chamber
2 (not shown) to the loadlock from the direction shown by the arrow, and placed on
3 supports 78, 80.

4 The cassette 50 may then be lowered to place the processed substrate 82 onto
5 the cooling plate 52 for cooling, as shown in Fig. 7d. Preferred embodiments may include
6 structures such as pins 57 extending from the cooling plate 52 into openings 61 in the
7 bottom of the middle plate 56. The pins 57 may act to ensure proper alignment of the
8 cooling plate 52 and middle plate 56 as well as providing a barrier to prevent a substrate
9 from sliding off of the cooling plate in a lateral direction, which may occur due to a gas
10 pressure introduced in the chamber during a cooling procedure. As can be seen in Fig.
11 7d, the cooling plate 52 and middle plate 56 may be positioned so that the processed
12 substrate 82 is essentially sandwiched between the plates. This promotes the efficient
13 cooling of the processed substrate 82. In general, the closer the middle plate 56 is
14 positioned to the processed substrate 82, the faster the cooling rate of the processed
15 substrate 82. In one example, a 5 mm gap between the middle plate 56 and the
16 processed substrate 82 provided a cooling rate that was about 5 times faster than a 1
17 inch (~25 mm) gap.

18 Fig. 7d also shows that the unprocessed substrate 92 has also been placed into
19 alignment for delivery through the vacuum opening 98 in the direction indicated by the
20 arrow. The unprocessed substrate is delivered through the vacuum opening and then the
21 vacuum door 99 is closed and the chamber vented so that another unprocessed substrate
22 92' may be placed onto the upper support 88, 90 through the atmospheric opening, from
23 the direction indicated by the arrow, as illustrated in Fig. 7e. The venting may also be
24 controlled to promote uniform cooling of the processed substrate 82. The cassette 50
25 may then be raised to lift the processed substrate off of the cooling plate 52 and into
26 position to be removed from the loadlock through the atmospheric opening 96 in the
27 direction indicated by the arrow, as shown in Fig. 7f.

28 It should be appreciated that the above steps may be varied as desired and that
29 there are numerous different processing schemes that may be performed according to
30 embodiments of the present invention. For example, another processing embodiment
31 may include heating the unprocessed substrate 92 in the loadlock prior to transferring it to
32 the transfer chamber. In such an embodiment the heating step is carried out and the
33 heated, unprocessed substrate 92 is preferably delivered through the vacuum opening 98
34 to the transfer chamber prior to delivering the processed substrate 82 from the transfer
35 chamber to the loadlock.

1 More detailed views of the cassette 50 and the cooling plate 52 are illustrated in
2 Figs. 8 and 9. The upper plate 54, middle plate 56, and lower plate 76 may be coupled
3 together through side portions 77, 79. The side portions 77, 79 may be separate pieces
4 coupled together using pins 89. Alternatively, the side portions 77, 79 may be a single
5 unit and may be integrated into one or more of the plates 54, 56 and 76.

6 As seen in Fig. 8, the lower supports 78, 80 are supporting processed substrate
7 82 above the surface of the cooling plate 52. This configuration may correspond to a
8 load/unload condition where a processed substrate 82 is being loaded into or removed
9 from the loadlock. In this embodiment the processed substrate 82 is transparent. The
10 supports 78, 80 may have a variety of structures that can support a substrate including,
11 but not limited to a pin, bolt, screw or peg-like shape. The tips of the supports may also
12 have variety of structures. For example, as illustrated in Figs. 7a, the tip of the supports
13 78, 80, 88, 90 are rounded, whereas in Fig. 9, the tips of the supports 78, 80 are flat and
14 include openings 81. As illustrated in Figs. 8 and 9, one embodiment preferably includes
15 four outer pins 78 and two central pins 80.

16 Fig 9 illustrates the position of the lower supports 78, 80 after the supports have
17 been lowered to place the processed substrate 82 on the surface of the cooling plate 52.
18 The cooling plate 52 may be designed to have one or more zones for preferentially
19 controlling the temperature of a substrate thereon. This may be accomplished by
20 providing a pattern of one or more channels or grooves 104 on its upper surface. The
21 location and number of grooves 104 is designed to control the contact area between a
22 substrate and the surface of the cooling plate 52 to permit better temperature control
23 during cooling. For example, if more grooves 104 per unit area are located near the
24 periphery of the cooling plate 52 than near the center, an increased surface area of the
25 substrate will contact the cooling plate 52 near its center. If the center is a heat
26 transmissive material such as, for example, a metal, then more heat will be transmitted
27 from the center of the substrate. The grooves 104 are designed to counter the thermal
28 losses, which typically occur more quickly near the periphery of the substrate. This leads
29 to a more uniform temperature distribution across the substrate during cooling. In one
30 embodiment the grooves 104 may have a width of about 6 mm and a depth of about 1
31 mm. Other dimensions may be suitable for particular applications.

32 Embodiments may also include a one or more coolant carrying channels
33 incorporated into or attached to portions of a cooling plate and a middle plate in order to
34 remove heat from the plate quickly. The coolant carrying channels may be distributed
35 along the cooling plate as desired to yield different cooling characteristics for different

1 portions of the cooling plate, in order to provide a more uniform temperature distribution
2 across a substrate. Fig. 10 illustrates a cross-sectional view of an embodiment of a
3 cooling plate 106 including a number of grooves 104 and a coolant carrying channel 108
4 formed therein. Fig. 11 illustrates an embodiment of a cooling plate 110 including
5 grooves 104 and a pipe or tube 112 as a coolant carrying channel connected
6 (permanently or detachably) to the bottom of the cooling plate 110. In certain
7 embodiments, the middle plate acts like a second cooling plate to assist in cooling a
8 processed substrate. Fig. 12 illustrates an embodiment of a middle plate 116 including a
9 coolant carrying channel 118 therein. Fig. 13 illustrates an embodiment of a middle plate
10 120 having a pipe or tube 122 as a cooling carrying channel connected (permanently or
11 detachably) to the top of the middle plate 120.

12 Embodiments may also include a cooling plate and a middle plate each including a
13 surface having multiple characteristics such as a different surface finish in different
14 locations. For example, a dull and/or black finish (or other dark color finish) may
15 accelerate cooling due to greater heat absorption than a reflective and/or smooth finish,
16 which will reflect more heat back to the substrate. Anodizing or bead blasting all or part of
17 the cooling plate can form a preferred high emissivity finish that may accelerate cooling.
18 As illustrated in Fig. 14, for example, the surface of a plate 130 (such as a cooling plate
19 and/or a middle plate) may contain a high emissivity central area 131. As seen in fig. 14,
20 the high emissivity central area 131 of the plate 130 is viewed through a transparent
21 substrate 132. The substrate 132 preferably has a larger size than the high emissivity
22 area 131 (and a smaller size than the plate 130). In certain embodiments, in order to
23 more uniformly cool the substrate it is desirable to not provide the high emissivity region
24 130 near the edges of the substrate 132. This is because the edges of the substrate 132
25 tend to cool more quickly than its center area, so providing the high emissivity region 130
26 over the entire surface would lead to the edges of the substrate 132 cooling much faster
27 than the central area. Such non-uniform cooling can cause undesirable stresses and/or
28 warping of the substrate 132.

29 The top and bottom covers 70, 72 (Fig. 2) of the loadlock 30 may include flanges
30 116 and o-rings 118, which are used to mount the top cover 70 and lower cover 72 to the
31 loadlock frame member 64. Top cover 70 may also include inlet/outlet vent 120, which
32 may include a gas delivery pipe or tube through which a gas may be delivered to the
33 interior of the loadlock. A variety of gases may be delivered to the loadlock depending on
34 the processing operation (cooling, annealing, preheating, ashing, etc.) to be carried out.
35 In certain embodiments, it is preferred that a cooling gas is delivered into the chamber

1 upon venting to assist in cooling a processed substrate on the cooling plate 52. Preferred
2 cooling gases for use in the chamber include nitrogen and/or helium. Other inert gases
3 including, but not limited to argon and neon could also be used. Certain embodiments
4 utilize a mixture of helium and nitrogen at pressures of about 754-759 torr nitrogen and
5 about 1-6 torr helium. In one preferred embodiment, cooling gas is supplied to the
6 chamber by venting the chamber at 3 torr helium and 757 torr nitrogen. This cooling
7 scheme has been observed to provide a uniform and rapid cooling. Preferred
8 embodiments may also include helium alone as the cooling gas due to its inert nature and
9 thermal conductivity. It is preferred that the substrate be cooled with a uniformity of about
10 100°C or less along the substrate, even more preferably about 50°C or less. If desired a
11 filter 122 (Fig. 2) may be positioned near the top of the loadlock to filter out undesirable
12 particles and to promote uniform distribution of gas throughout the loadlock chamber.
13 The filter 122 may be held in place by holder 124 and may be adjusted using screw 126.

14 In certain preferred embodiments, the lower supports 78, 80 extend through
15 apertures in the cooling plate 52. Alternative embodiments may utilize a lower support
16 extending adjacent to the cooling plate instead of through the apertures in the cooling
17 plate. As illustrated in Fig. 15, one such embodiment may include a support 136 adjacent
18 to a cooling plate 138 including one or more movable arms 140 which may be lowered
19 into one or more grooves 142 in the cooling plate 138 in order to deposit a processed
20 substrate 82 on the upper surface of the cooling plate 138.

21 Other embodiments may include a loadlock having components similar in some
22 ways to those illustrated in 6a, but including a single opening for transferring substrates in
23 and out of the loadlock and between the loadlock and a transfer chamber.

24 Several embodiments of cluster processing systems according to embodiments of
25 the present invention are illustrated in Figs. 16 and 17. Fig. 16 illustrates a system 158
26 which, according to one embodiment, includes a supply of unprocessed substrates from
27 an unprocessed substrate cassette 162, which may be supplied to the loadlock 160 from
28 a substrate cassette and robot station 164 one at a time using a robot 166. The loadlock
29 160 may have a similar structure to the loadlock 30 shown in Figs. 2-4. Once an
30 unprocessed substrate is inside the loadlock 160, the loadlock 160 is evacuated and the
31 unprocessed substrate is transported to the transfer chamber 168 having a second robot
32 170 therein. Once inside the transfer chamber 168, the unprocessed substrate is
33 transferred between chambers for processing. In one embodiment, the substrate is first
34 transported to chamber 172 for heating, then back to the transfer chamber 168, and then
35 to another processing chamber 174, which may be any other type of processing chamber

1 such as, for example, a chemical vapor deposition (CVD) chamber, a physical vapor
2 deposition (PVD) chamber, or an etching chamber. After treatment in a processing
3 chamber 174, the substrate may be transported to the transfer chamber 168 and then to
4 another processing chamber 174. When the substrate is fully processed as desired, it is
5 then delivered from the final processing chamber to the transfer chamber 168 and back to
6 the loadlock 160. The processed substrate may then be cooled in the loadlock 160.
7 Cooling may take place while the loadlock 160 is evacuated and may also take place as
8 the loadlock 160 is vented. Once venting is complete and the processed substrate is
9 sufficiently cooled (such as, for example, to about 100°C), the processed substrate may
10 be removed from the loadlock 160 using the robot 166 and delivered to a processed
11 substrate cassette 176 at the station 164.

12 Another embodiment of a processing system 178 in some ways similar to that of
13 Fig. 16 is illustrated in Fig. 17. However, the embodiment of Fig. 17 includes two
14 loadlocks 160 and five processing chambers 174, as well as one heating chamber 172
15 and transfer chamber 168 having a robot 170 therein. This embodiment may be
16 particularly useful when the processing can be carried out quickly and throughput can be
17 increased by supplying more substrates to the system. As illustrated, the system 178
18 includes a larger station 165 having more cassettes 162, 176 for supplying unprocessed
19 substrates to the loadlocks 160 and for accepting processed substrates from the
20 loadlocks 160 using the robot 167. Certain embodiments of the present invention may
21 include a heater within the loadlock. When using such embodiments, it may be possible
22 to eliminate the heating chamber such as heating chamber 172 of Figs. 16 and 17. In
23 such a case an additional processing chamber 174 may be used if desired, and if only
24 one loadlock 160 is used, the system will have seven processing chambers. Depending
25 on the desired processing steps and the platform used, any number of processing
26 chambers, loadlocks, and heating chambers may be used. Certain platforms may also
27 utilize more than one transfer chamber.

28 Selected embodiments of the present invention can provide one or more of a
29 number of advantages. For example, in certain embodiments, a single loadlock chamber
30 can be used for both cooling processed substrates and heating unprocessed substrates.
31 Various features also enable a large glass substrate to be cooled or heated quickly,
32 thereby increasing the throughput of the system. Various aspects of the loadlock design
33 may help to control the temperature of a substrate on the cooling plate to provide a more
34 uniform temperature across the substrate or to provide a particular temperature
35 distribution across the substrate. For example, the heating device 94 may in certain

embodiments be used during a cooling operation in order to control the temperature distribution across a substrate. By controlling the insulative properties of the middle plate 56 and/or other portions of the loadlock, heat from the heating device 94 may be transmitted to a portion of a substrate in order to control its temperature. In one embodiment, by keeping the outer edges of the substrate at a higher temperature than the middle regions of the substrate, the outer edges can be placed into compression as the substrate cools, thus minimizing the risk of edge failures. Cooling the outer edges of a substrate at a slower rate than the interior portions of the substrate may be accomplished in certain embodiments by directed an amount of heat from the heating element 94 around the edges of the middle plate 56 to contact the outer edge regions of the processed substrate on the cooling plate 52.

In addition, the time spent waiting during processed substrate cooling and unloading from the loadlock can be significantly shorter when using a dual substrate cassette according to embodiments of the present invention, as compared to using a loadlock having a larger cassette holding, for example, 12 substrates. In a system having a cassette holding 12 substrates in the loadlock, it may take approximately 2 minutes for the system to vent and another 8 minutes to unload the substrates from the loadlock after it has been vented when using a robot arm to unload each substrate. Certain embodiments of the present invention (which have a considerably smaller interior chamber volume than a loadlock having a 12 substrate cassette therein) may preferably accomplish both the venting and removal of a processed substrate in a time of up to about a minute, or more preferably about 30 seconds. In addition, certain embodiments which have a heating element in the loadlock can heat a substrate quickly due to the relatively small interior volume in the loadlock and because the substrate can be located close to the heater. Preferred embodiments can heat the substrate in a time of less than one minute, or more preferably about 30 seconds.

The faster venting, substrate removal, and/or heating time provided by selected embodiments of the present invention offer several advantages. First, the throughput of the system may, for certain types of processing, be higher. Certain embodiments can permit a fast tact time, which is the time it takes one substrate to enter the system, be processed, and then exit the system. Second, the need to use a robot having the greatest speed possible (for unloading the substrates) may be reduced because the system can have less down time. Using a slower speed robot may improve the reliability of the processing system.

Depending on the processing steps to be carried out, it may in certain

1 embodiments be desirable to have 0 or 1 substrate in the loadlock at any one time. In
2 other embodiments, it may be desirable to have up to 2 substrates in the loadlock at any
3 one time. Alternative embodiments may permit more than 2 substrates to be located in
4 the loadlock at any one time. Selected embodiments of the present invention may
5 achieve a high throughput despite having fewer substrates in the system at any one time
6 than in certain other systems. For example, one batch processing system having a
7 substrate cassette in the loadlock may at certain times have approximately 40 substrates
8 in the system, with 12 substrates in the loadlock, 12 substrates in a heating chamber, and
9 16 substrates being processed in the other system chambers. Matching the number of
10 substrates in the loadlock and heating chamber can permit smooth substrate transferring
11 due to a symmetrical layout of the system. A system according to certain preferred
12 embodiments of the present invention may at certain times have approximately 15
13 substrates in the system, with 1 in the loadlock, 8 in a heating chamber, and 6 substrates
14 in the other system chambers. These numbers may vary considerably depending on the
15 configuration of the various chambers in the system. Depending on the exact processing
16 steps and their duration, due to the faster insertion and removal of substrates, certain
17 embodiments of the present invention may have a higher overall throughput per time
18 period than a system that having a 12-substrate cassette in the loadlock.

19 The smaller size of the loadlock dual substrate cassette of certain embodiments of
20 the present invention relative to the loadlock cassettes used in some other systems also
21 enables to loadlock to be fabricated from less material and to utilize smaller vacuum,
22 elevator, power components and the like. These smaller components can make the
23 system considerably less expensive than larger systems including multiple substrate
24 cassettes within the loadlock.

25 Typical processing pressures used in the various chambers described above may
26 range from about 10^{-8} torr to several torr and vary depending on the chamber and the
27 process steps (PVD, CVD, etching, annealing, etc) being performed. It is generally
28 desired that the pressure difference between adjacent chambers be kept to a minimum or
29 controlled when adjacent chambers are in communication with each other in order to
30 minimize contamination.

31 Embodiments of the present invention also include other types of processing
32 systems such as linear systems in which a substrate may be transported from a loadlock
33 to one or more processing chambers sequentially and then to the same or another
34 loadlock, depending on the system layout.

35 It will, of course, be understood that modifications of the present invention, in its

1 various aspects, will be apparent to those skilled in the art. A variety of additional
2 embodiments are also possible, their specific designs depending upon the particular
3 application. As such, the scope of the invention should not be limited by the particular
4 embodiments herein described but should be defined by the claims.

WHAT IS CLAIMED IS:

1. A loadlock comprising:
 - a first support structure adapted to support a first substrate; and
 - a cooling plate adapted to support a second substrate.
2. A loadlock as in claim 1, wherein said cooling plate is disposed below said first support structure.
3. A loadlock as in claim 1, further comprising a second support structure disposed below said first support structure, said second support structure being moveable relative to said cooling plate.
4. A loadlock as in claim 3, wherein said cooling plate is positioned to accept a processed substrate from said second support structure.
5. A loadlock as in claim 1, wherein said cooling plate includes at least one groove on its surface.
6. A loadlock as in claim 5, wherein said cooling plate further includes at least one coolant carrying channel.
7. A loadlock as in claim 1, wherein said cooling plate includes an anodized surface region.
8. A loadlock as in claim 3, further comprising an elevator to control the vertical position of said first support structure and said second support structure.
9. A loadlock as in claim 8, wherein said second support structure extends through said cooling plate.
10. A loadlock as in claim 8, further comprising an unprocessed substrate on said first support structure and a processed substrate on said second support structure.

1 11. A loadlock as in claim 10, wherein said unprocessed substrate comprises a
2 glass material.

1 12. A loadlock as in claim 1, further comprising a heating device disposed
2 above said first support structure.

1 13. A loadlock as in claim 8, further comprising a moveable cassette which
2 includes said first support structure and second support structure.

1 14. A loadlock as in claim 13, further comprising a loadlock body portion which
2 defines a first aperture adapted to accept unprocessed substrates into said loadlock and a
3 second aperture adapted to receive a processed substrate.

1 15. A loadlock as in claim 14, wherein said elevator is adapted to elevate said
2 cassette, and said cooling plate is coupled to said loadlock body portion.

1 16. A loadlock as in claim 13, wherein said cassette further comprises a first
2 plate and said first support structure is coupled to said first plate.

1 17. A loadlock as in claim 16, wherein said first plate and said cooling plate
2 each include a first surface region having a first emissivity and a second surface region
3 having a second emissivity, said second emissivity being greater than said first emissivity.

1 18. A loadlock as in claim 16, wherein said cassette further comprises a
2 second plate located below said cooling plate and said second support structure is
3 coupled to said second plate.

1 19. A loadlock as in claim 18, wherein said cassette further comprises a third
2 plate located above said first support structure.

1 20. A loadlock as in claim 19, further comprising a heating device located
2 above said third plate.

1 21. A loadlock as in claim 16, further comprising a filter disposed above said
2 first support structure.

1 22. A loadlock comprising:
2 a chamber body;
3 a first support structure in said chamber body adapted to support one
4 unprocessed substrate;
5 a second support structure in said chamber body adapted to support one
6 processed substrate;
7 said first support structure being disposed above said second support structure;
8 an elevator to control the vertical position of said first support structure and said
9 second support structure;
10 a first aperture to permit insertion of an unprocessed substrate into said loadlock
11 and removal of a processed substrate from said loadlock;
12 a second aperture to permit removal of an unprocessed substrate from said
13 loadlock and insertion of a processed substrate into said loadlock;
14 a cooling plate including a surface adapted to support a processed substrate
15 thereon; and
16 a heating device located above said first support.

1 23. A loadlock as in claim 22, wherein said second support structure extends
2 through said cooling plate when positioned to support one processed substrate.

1 24. A loadlock as in claim 22, wherein said first support structure and said
2 second support structure are movable relative to said cooling plate.

1 25. A loadlock as in claim 24, wherein said cooling plate is attached to said
2 chamber body.

1 26. A loadlock as in claim 25, wherein said cooling plate has a plurality of holes
2 therein to permit said second support structure to move therethrough.

1 27. A loadlock as in claim 22, further comprising a middle plate between said
2 first support structure and said second support structure.

1 28. A loadlock as in claim 27, wherein said cooling plate includes at least one
2 structure extending therefrom and said middle plate includes at least one opening sized to
3 accommodate said at least one structure extending from said cooling plate.

1 29. A loadlock as in claim 27, wherein said first support structure is connected
2 to said middle plate.

1 30. A loadlock as in claim 27, wherein said middle plate includes a cooling
2 layer and an insulation layer.

1 31. A loadlock as in claim 22, further comprising a heating element disposed
2 above said first support.

1 32. A loadlock as in claim 22, wherein said first support structure comprises a
2 plurality of pins and said second support structure comprises a plurality of pins.

1 33. A semiconductor processing system comprising:
2 at least one processing chamber;
3 a transfer chamber connected to said at least one processing chamber; and
4 a loadlock connected to said transfer chamber, said loadlock comprising:
5 a single substrate upper support and a single substrate lower support;
6 a transfer aperture to transfer a single substrate between said transfer
7 chamber and said loadlock;
8 an elevator to raise and lower said single substrate upper support and said
9 single substrate lower support; and
10 a cooling plate disposed in said loadlock and positioned to accept a single
11 substrate from said single substrate lower support.

1 34. A semiconductor processing system as in claim 33, wherein said single
2 substrate lower support extends through said cooling plate.

1 35. A semiconductor processing system as in claim 33, wherein said loadlock
2 further comprises a load/unload aperture through which an unprocessed substrate may

3 be loaded into said loadlock and through which a processed substrate may be unloaded
4 from said loadlock.

1 36. A semiconductor processing system as in claim 35, wherein said loadlock
2 further comprises a transfer aperture through which an unprocessed substrate may be
3 delivered from said loadlock to said transfer chamber and through which a processed
4 substrate may be delivered from said transfer chamber to said loadlock.

1 37. A semiconductor processing system as in claim 35, wherein said loadlock
2 further comprises a heating element.

1 38. A semiconductor processing system as in claim 36, wherein said loadlock
2 further comprises a heating element and said heating element is disposed above said
3 single substrate upper support.

1 39. A semiconductor processing system as in claim 38, wherein said loadlock
2 further comprises a middle plate disposed above said cooling plate and below said
3 heating element.

1 40. A semiconductor processing system as in claim 39, wherein said single
2 substrate upper support is connected to said middle plate.

1 41. A semiconductor processing system as in claim 40, further comprising a
2 gas inlet to supply a gas to said loadlock.

1 42. A semiconductor processing system as in claim 41, wherein said loadlock
2 includes a top surface, said gas inlet being located along said top surface of said
3 loadlock.

1 43. A semiconductor processing system as in claim 35, further comprising at
2 least one processing chamber coupled to said transfer chamber, said at least one
3 processing chamber consisting of at least one chamber selected from the group
4 consisting of a physical vapor deposition chamber, a chemical vapor deposition chamber,
5 an etching chamber, and a heating chamber.

1 44. A semiconductor processing system as in claim 43, further comprising:
2 an external substrate supply station comprising:
3 a first robot to deliver substrates to said loadlock and pick up substrates from said
4 loadlock;
5 at least one unprocessed substrate cassette to supply unprocessed substrates to
6 said loadlock; and
7 at least one processed substrate cassette to accept processed substrates from
8 said loadlock.

1 45. A semiconductor processing system as in claim 44, further comprising a
2 second robot to transfer a substrate between said loadlock and said transfer chamber.

3 46. A semiconductor processing system as in claim 36, further comprising:
4 a transfer chamber robot to transfer a substrate between said loadlock and said
5 transfer chamber;
6 at least one processing chamber coupled to said transfer chamber, said at least
7 one processing chamber consisting of at least one chamber selected from the group
8 consisting of a physical vapor deposition chamber, a chemical vapor deposition chamber,
1 an etching chamber, and a heating chamber.

2 47. A semiconductor processing system as in claim 46, further comprising a
3 loadlock delivery robot to transfer an unprocessed substrate into said loadlock and
4 remove a processed substrate from said loadlock.

1 48. A semiconductor processing system as in claim 33, further comprising a
2 substrate disposed on said cooling plate and a cooling gas comprising helium disposed in
3 said loadlock.

1 49. A semiconductor processing system as in claim 48, wherein said cooling
2 gas further comprises nitrogen.

1 50. A loadlock system comprising:
2 a loadlock chamber;
3 a support structure disposed in said chamber, said support structure adapted to
4 accept a single substrate from a robot arm;
5 a cooling plate disposed in said chamber; said cooling plate positioned to accept a
6 single substrate from said support structure; and
7 wherein said support structure is movable relative to said cooling plate.

1 51. A loadlock system as in claim 50, wherein said cooling plate includes at
2 least one aperture through which said support structure may extend.

1 52. A loadlock system as in claim 50, further comprising a heating device
2 disposed in said loadlock chamber, said heating device being located above said support
3 structure and said cooling plate.

1 53. A loadlock system comprising:
2 first means for supporting only a single unprocessed substrate;
3 second means for supporting only a single processed substrate;
4 said first means being located above said second means; and
5 delivery means for delivering a processed substrate to a cooling plate in said
6 loadlock system.

1 54. A loadlock system as in claim 53, further comprising cooling means for
2 cooling said substrate on said cooling plate.

1 55. A loadlock system as in claim 53, further comprising heating means for
2 heating a substrate, said heating means disposed above said first support.

1 56. A method for using a loadlock comprising:
2 delivering an unprocessed substrate to an upper support structure in said loadlock
3 through an opening in said loadlock;
4 closing said opening and evacuating said loadlock;
5 transferring said unprocessed substrate to a chamber outside of said loadlock;
6 delivering a processed substrate from said chamber outside of said loadlock to a

7 lower support structure in said loadlock;
8 delivering said processed substrate from said lower support structure to a cooling
9 plate in said loadlock; and
10 cooling said processed substrate.

1 57. A method as in claim 56, wherein said cooling includes introducing a gas
2 into said loadlock and filtering said gas as it enters said loadlock.

1 58. A method as in claim 56, wherein said cooling includes introducing a gas
2 comprising helium into said loadlock.

1 59. A method as in claim 56, wherein said cooling includes introducing a gas
2 comprising a helium gas and a nitrogen gas into said loadlock.

1 60. A method as in claim 59, wherein said gas includes said nitrogen gas
2 present at a pressure of about 754 to about 759 torr and said helium gas present at
3 about 1 to about 6 torr.

1 61. A method as in claim 58, wherein said gas consists essentially of 757 torr
2 nitrogen and 3 torr helium.

1 62. A method as in claim 56, further comprising heating said unprocessed
2 substrate in said loadlock prior to transferring said unprocessed substrate to said
3 chamber outside of said loadlock.

1 63. A method as in claim 56, further comprising heating said unprocessed
2 substrate in said loadlock prior to transferring said unprocessed substrate to said
3 chamber outside of said loadlock.

1 64. A method as in claim 56, wherein said cooling said processed substrate
2 includes providing a cooling fluid to said cooling plate to transfer heat away from said
3 cooling plate.

1 65. A method as in claim 56, wherein said delivering said processed substrate

2 to said cooling plate comprises lowering at least a portion of said lower support structure
3 through said cooling plate so that a lower surface of said processed substrate is placed
4 onto an upper surface of said cooling plate.

1 66. A method as in claim 65, wherein said lowering at least a portion of said
2 lower support structure through said cooling plate comprises lowering a top of said lower
3 support structure to a position lower than said upper surface of said cooling plate.

1 67. A method as in claim 56, further comprising positioning a second plate
2 above said processed substrate at a position so that heat from said processed substrate
3 is transmitted to said second plate.

1 68. A method as in claim 56, further comprising supplying a cooling fluid to
2 cool said second plate and said cooling plate.

1 69. A method for processing substrates comprising:
2 delivering an unprocessed substrate to an upper support structure in a loadlock
3 through a first opening in said loadlock;
4 closing said first opening and evacuating said loadlock;
5 delivering said unprocessed substrate to a chamber outside of said loadlock
6 through a second opening in said loadlock;
7 delivering a processed substrate from said chamber outside of said loadlock to
8 said lower support structure through said second opening in said loadlock; and
9 delivering said processed substrate to a cooling plate in said loadlock.

1 70. A method as in claim 69, wherein delivering said processed substrate to
2 said cooling plate comprises lowering said lower support structure relative to said cooling
3 plate.

1 71. A method as in claim 69, further comprising:
2 cooling said substrate on said cooling plate;
3 raising said lower support structure relative to said cooling plate to remove said
4 processed substrate from said cooling plate; and
5 removing said processed substrate from said loadlock through said first opening.

1 72. A method as in claim 71, further comprising venting said loadlock prior to
2 raising said lower support structure to remove said processed substrate from said cooling
3 plate.

1 73. A method as in claim 72, wherein said venting comprises delivering a
2 cooling gas to said loadlock.

1 74. A method as in claim 73, wherein said venting gas comprises helium.

1 75. A method as in claim 72, wherein said cooling said substrate on said
2 cooling plate, venting said loadlock, removing said processed substrate from said cooling
3 plate, and removing said processed substrate from said loadlock through said first
4 opening is carried out in a time of no greater than 60 seconds.

1 76. A method as in claim 72, further comprising heating said processed
2 substrate in said loadlock prior to venting said loadlock.

1 77. A method as in claim 75, wherein said time is no greater than 30 seconds.

1 78. A method as in claim 77, wherein said unprocessed substrate is preheated
2 in said loadlock prior to delivering said unprocessed substrate to a chamber outside of
3 said loadlock, and said preheating is carried out in a time of no greater than 60 seconds.

1 79. A method as in claim 78, wherein said preheating is carried out in a time of
2 no greater than 30 seconds.

1 80. A method as in claim 71, further comprising:
2 lowering said lower support structure relative to said first opening after removing
3 said processed substrate from said loadlock through said first opening; and
4 aligning said upper support structure to accept an unprocessed substrate on upper
5 support structure through said first opening.

1 81. A method as in claim 69, further comprising heating said unprocessed
2 substrate in said loadlock.

1 82. A method as in claim 81, wherein said heating is carried out in a time of no
2 greater than 60 seconds.

1 83. A method as in claim 81, wherein said heating is carried out for no greater
2 than 30 seconds.

1 84. A method as in claim 71, wherein said cooling said substrate on said
2 cooling plate includes positioning a second late above said substrate, said second plate
3 positioned so that heat from said substrate is transferred to said second plate.

1 85. A method as in claim 84, wherein said second plate is positioned
2 approximately 5 mm from said substrate.

1 86. A method as in claim 84, further comprising positioning at least one pin
2 extending from said cooling plate to said middle plate.

1 87. A method as in claim 69, wherein said delivering said processed substrate
2 from said chamber outside of said loadlock to said lower support structure is carried out
3 prior to delivering said unprocessed substrate to said chamber outside of said loadlock.

1 88. A method as in claim 87, further comprising heating said unprocessed
2 substrate in said loadlock prior to delivering said unprocessed substrate to a chamber
3 outside of said loadlock.

1 89. A method as in claim 69, wherein said delivering said unprocessed
2 substrate is carried out after said delivering said processed substrate.

1 90. A method for processing a substrate comprising:
2 delivering one unprocessed substrate from an unprocessed substrate supply to a
3 first loadlock support structure using a first robot;
4 transferring said unprocessed substrate from said loadlock to a transfer chamber

5 using a second robot;
6 transferring said unprocessed substrate from said transfer chamber to at least one
7 processing chamber to process said unprocessed substrate to form a processed
8 substrate;
9 transferring said processed substrate from said at least one processing chamber
10 to said transfer chamber;
11 transferring said processed substrate from said transfer chamber to a second
12 loadlock support structure in said loadlock using said second robot;
13 transferring said processed substrate from said second loadlock support structure
14 to a cooling plate in said loadlock;
15 cooling said processed substrate; and
16 removing said processed substrate from said loadlock using said first robot.

1 91. A method as in claim 90, further comprising heating said unprocessed
2 substrate in said loadlock prior to transferring said unprocessed substrate from said
3 loadlock to said transfer chamber.

1 92. A method as in claim 90, further comprising positioning a heater in said
2 loadlock above said first loadlock support structure.

1 93. A method as in claim 90, wherein said cooling said processed substrate
2 includes venting said loadlock prior to removing said processed substrate from said
3 loadlock, said venting including introducing a gas comprising helium into said loadlock.

1 94. A method as in claim 90, further comprising positioning said first support
2 structure above said second support structure in said loadlock.

1 95. A method for processing substrates comprising:
2 delivering a single unprocessed substrate to an upper support structure in said
3 loadlock,
4 evacuating said loadlock;
5 delivering said single unprocessed substrate from said loadlock to said transfer
6 chamber;
7 delivering a single processed substrate from a transfer chamber to a lower support

8 structure in said loadlock;
9 delivering said single processed substrate from said lower support structure to a
10 cooling plate in said loadlock;
11 venting said loadlock;
12 delivering said single processed substrate to a location external to said loadlock
13 and said transfer chamber; and
14 delivering another single unprocessed substrate to said loadlock.

1 96. A method as in claim 95, further comprising heating said single
2 unprocessed substrate in said loadlock prior to delivering said single unprocessed
3 substrate to said transfer chamber.

1 97. A method as in claim 95, wherein said delivering said single processed
2 substrate from said lower support structure to said cooling plate comprises lowering said
3 lower support structure through said cooling plate and placing a lower surface of said
4 single processed substrate onto an upper surface of said cooling plate.

ABSTRACT

1 One embodiment relates to a loadlock having a first support structure therein to
2 support one unprocessed substrate and a second support structure therein to support one
3 processed substrate. The first support structure is located above the second support
4 structure. The loadlock includes an elevator to control the vertical position of the support
5 structures. The loadlock also includes a first aperture to permit insertion of an
6 unprocessed substrate into the loadlock and removal of a processed substrate from the
7 loadlock, as well as a second aperture to permit removal of an unprocessed substrate
8 from the loadlock and insertion of a processed substrate into the loadlock. A cooling plate
9 is also located in the loadlock. The cooling plate includes a surface adapted to support a
10 processed substrate thereon. A heating device may be located in the loadlock above the
11 first support structure.

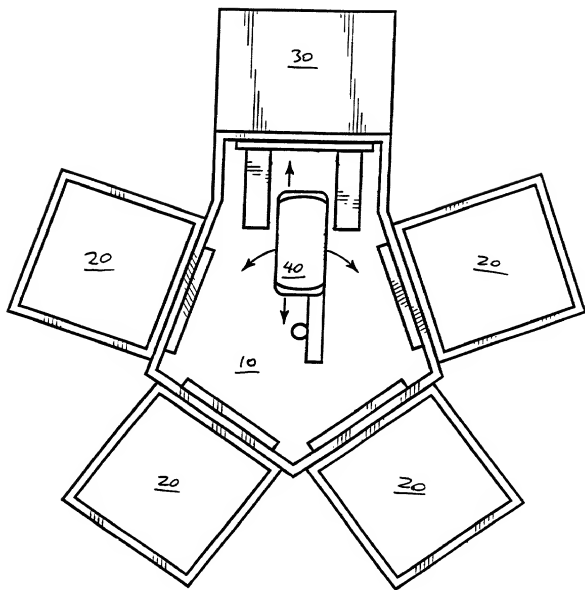


Fig. 1

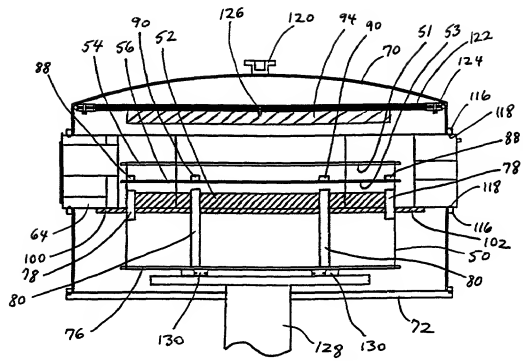
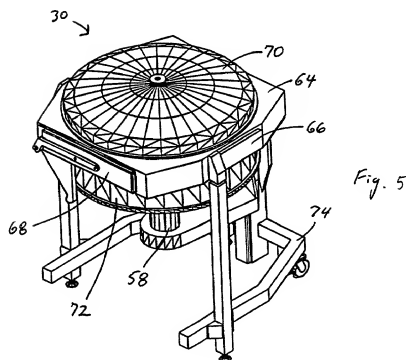
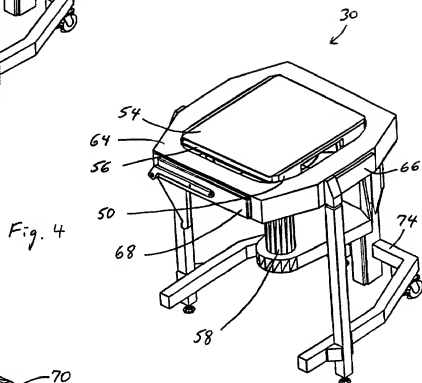
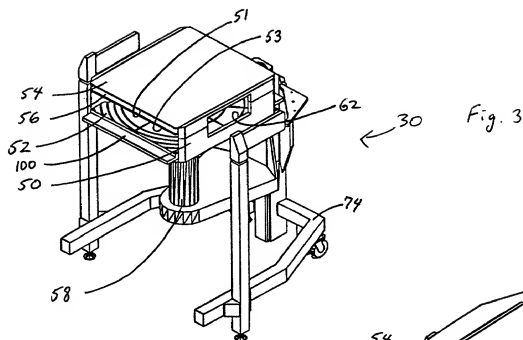


Fig. 2



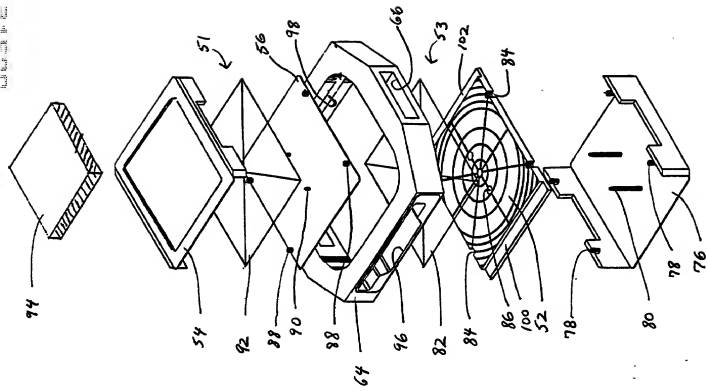


Fig. 6a

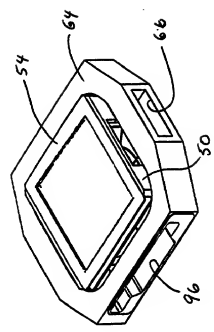


Fig. 6b

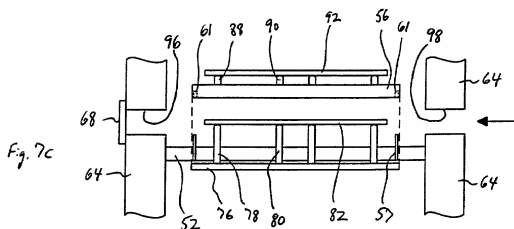
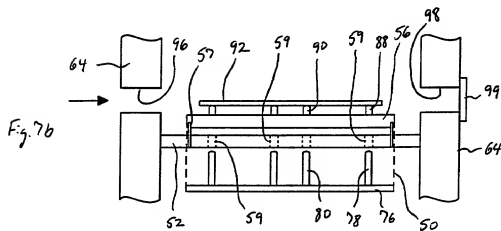
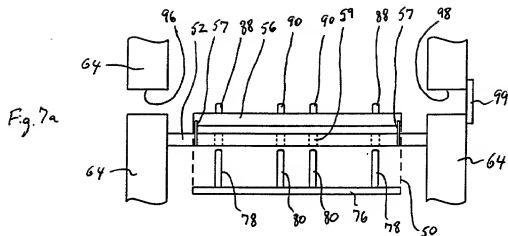


Fig. 7d

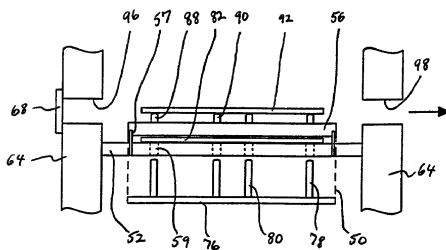


Fig. 7e

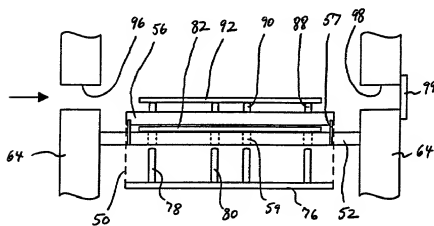
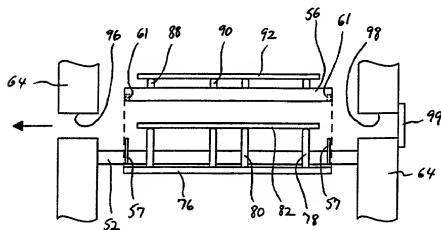


Fig. 7f



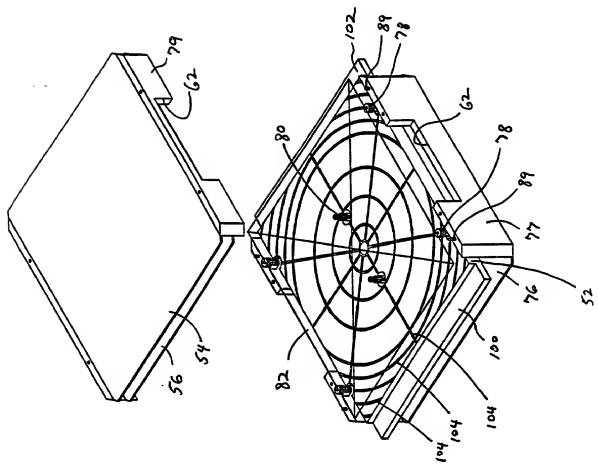


Fig. 8

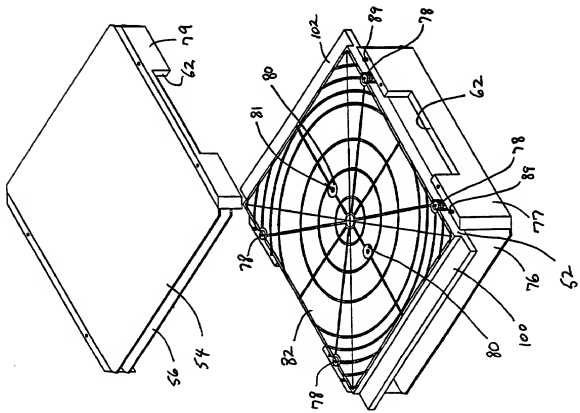


Fig. 9

Fig. 10

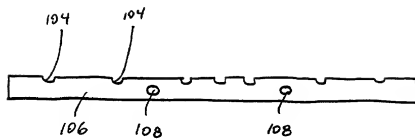


Fig. 11

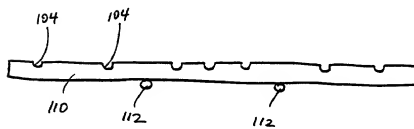


Fig. 12

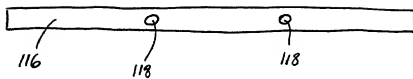
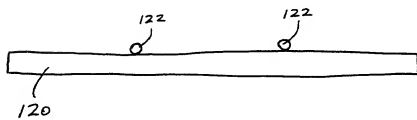


Fig. 13



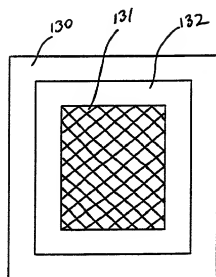


Fig. 14

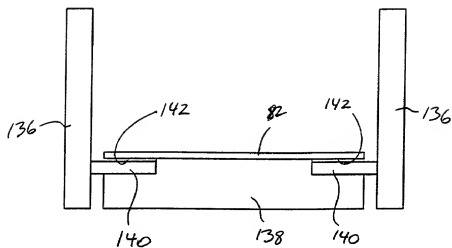


Fig. 15

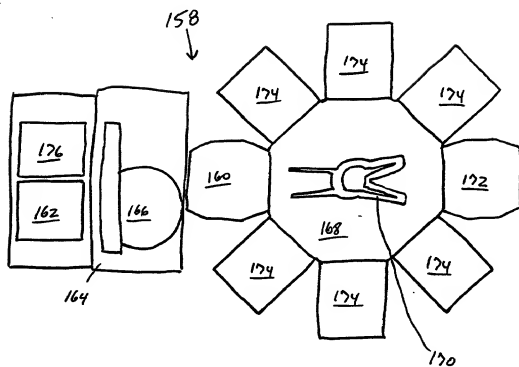


Fig. 16

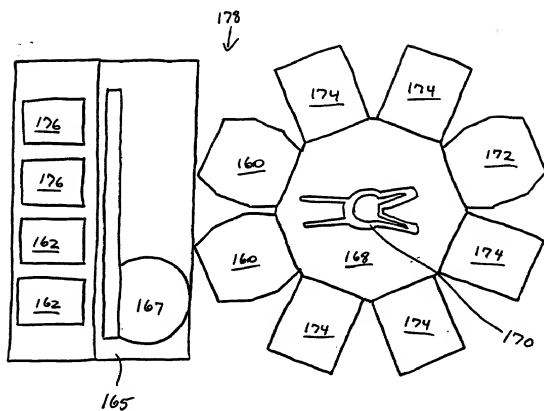


Fig. 17

COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

This declaration is of the following type:

- ☒ original
- ☐ divisional
- ☐ continuation
- ☐ continuation-in-part

INVENTORSHIP IDENTIFICATION

My residence, post office address and citizenship are as stated below next to my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

TITLE OF INVENTION

"DUAL SUBSTRATE LOADLOCK PROCESS EQUIPMENT"

SPECIFICATION IDENTIFICATION

The specification of which:

- ☒ is attached hereto
- ☐ was filed on _____, under Serial No. _____, executed on even date herewith; or ☐ Express Mail No. _____ (as Serial No. not yet known) . and was amended on _____ (if applicable)
- ☐ was described and claimed in PCT International Application No. _____ filed on _____ and as amended under PCT Article 19 on _____.

ACKNOWLEDGMENT OF REVIEW OF PAPERS AND DUTY OF CANDOR

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information I know to be material to patentability in accordance with Title 37, Code of Federal Regulations, §1.56,

and which is material to the examination of this application; namely, information where there is a substantial likelihood that a reasonable Examiner would consider it important in deciding whether to allow the application to issue as a patent, and

- ☐ In compliance with this duty there is attached an Information Disclosure Statement in accordance with 37 CFR §1.98.

PRIORITY CLAIM (35 U.S.C. §119)

I hereby claim foreign priority benefits under Title 35, United States Code, §119, of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below, and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed.

- ☒ No such applications have been filed.
☐ Such applications have been filed as follows:

- A. Prior foreign/PCT application(s) filed within 12 mos. (6 mos. for design) prior to this application, and any priority claims under 35 U.S.C. §119

<u>Country/PCT</u>	<u>Application No.</u>	<u>Date Filed</u>	<u>Priority Claimed</u>
			<input type="checkbox"/> Yes <input type="checkbox"/> No
			<input type="checkbox"/> Yes <input type="checkbox"/> No

- B. All foreign application(s), if any, filed more than 12 mos. (6 mos. for design) prior to this U.S. application

Country:
Application No.:
Filing date:

PRIORITY CLAIM (35 U.S.C. §120)

I hereby claim the benefit under Title 35, United States Code, §120, of any United States application(s) or PCT international application(s) designating the United States of America that is/are listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in that/those prior application(s) in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information that is material to the examination of this application (namely, information where there is substantial likelihood that a reasonable Examiner would consider it important in deciding whether to allow the application to issue as a patent) which occurred between the filing date of the prior application(s) and the national or PCT international filing date of this application.

- ☒ No such applications have been filed.
☐ Such applications have been filed as follows:

				<u>Status</u>
<u>Serial No.</u>	<u>Filing Date</u>	<u>Patented</u>	<u>Pending</u>	<u>Abandoned</u>

POWER OF ATTORNEY

I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

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Donald VerPlancken	Registration No. 33,217
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Joseph Bach	Registration No. 37,771
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James C. Wilson	Registration No. 35,412
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DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and, further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Sec. 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

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(Declaration ends with this page)